

54ACT16827, 74ACT16827 20-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCAS163A – JUNE 1990 – REVISED APRIL 1996

- **Members of the Texas Instruments Widebus™ Family**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

54ACT16827 ... WD PACKAGE
74ACT16827 ... DL PACKAGE
(TOP VIEW)

1OE1	1	56	1OE2
1Y1	2	55	1A1
1Y2	3	54	1A2
GND	4	53	GND
1Y3	5	52	1A3
1Y4	6	51	1A4
V _{CC}	7	50	V _{CC}
1Y5	8	49	1A5
1Y6	9	48	1A6
1Y7	10	47	1A7
GND	11	46	GND
1Y8	12	45	1A8
1Y9	13	44	1A9
1Y10	14	43	1A10
2Y1	15	42	2A1
2Y2	16	41	2A2
2Y3	17	40	2A3
GND	18	39	GND
2Y4	19	38	2A4
2Y5	20	37	2A5
2Y6	21	36	2A6
V _{CC}	22	35	V _{CC}
2Y7	23	34	2A7
2Y8	24	33	2A8
GND	25	32	GND
2Y9	26	31	2A9
2Y10	27	30	2A10
2OE1	28	29	2OE2

description

The 'ACT16827 are noninverting 20-bit buffers composed of two 10-bit sections with separate output-enable signals. For either 10-bit buffer section, the two output-enable (1OE1 and 1OE2 or 2OE1 and 2OE2) inputs must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 10-bit buffer section are in the high-impedance state.

The 74ACT16827 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16827 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16827 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
(each 8-bit section)

INPUTS			OUTPUT
OE1	OE2	A	Y
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

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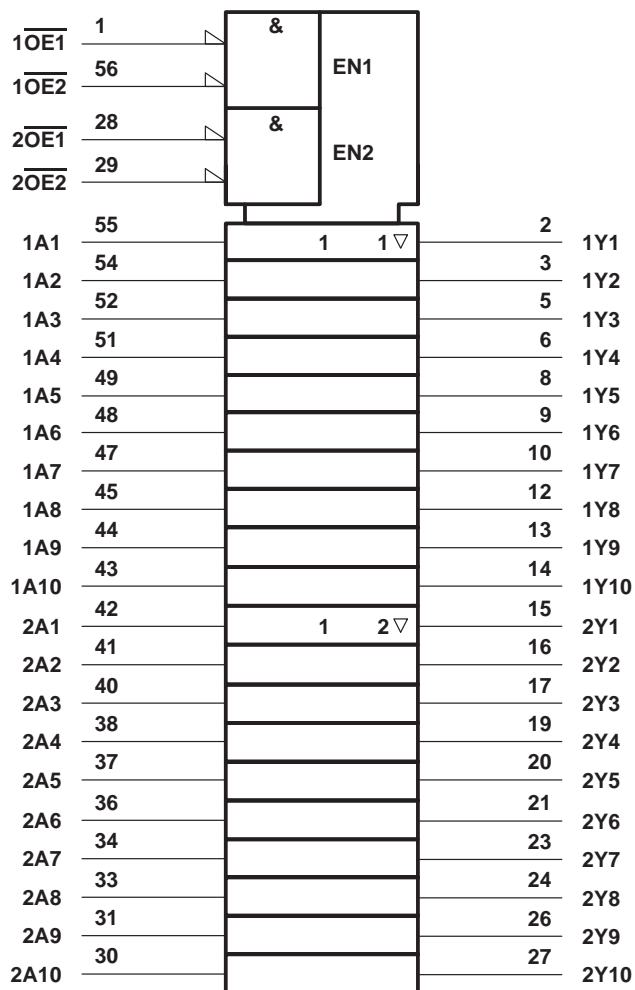
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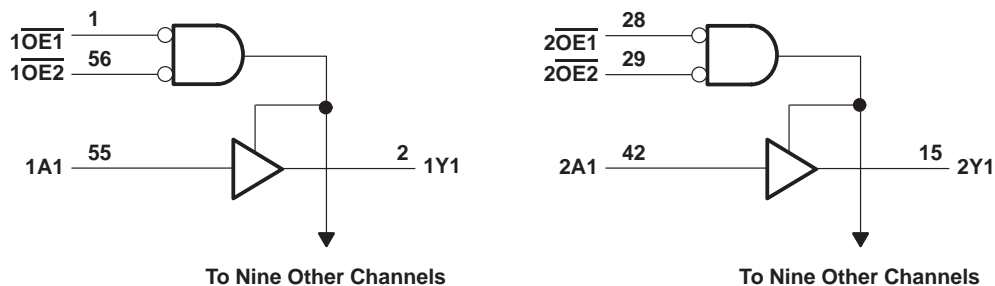
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	50 mA
Continuous current through V_{CC} or GND	±500 mA
Maximum package power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

	54ACT16827			54ACT16827			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8			0.8	V
V_I Input voltage	0		V_{CC}	0		V_{CC}	V
V_O Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH} High-level output current			–24			–24	mA
I_{OL} Low-level output current			24			24	mA
$\Delta t/\Delta v$ Input transition rise or fall rate	0		10	0		10	ns/V
T_A Operating free-air temperature	–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

54ACT16827, 74ACT16827

20-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			54ACT16827		74ACT16827		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 µA	4.5 V	4.4			4.4		4.4		V
		5.5 V	5.4			5.4		5.4		
	I _{OH} = -24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I _{OH} = -75 mA [†]	5.5 V				3.85		3.85		
V _{OL}	I _{OL} = 50 µA	4.5 V			0.1	0.1		0.1		V
		5.5 V			0.1	0.1		0.1		
	I _{OL} = 24 mA	4.5 V			0.36	0.44		0.44		
		5.5 V			0.36	0.44		0.44		
	I _{OL} = 75 mA [†]	5.5 V				1.65		1.65		
I _I	V _I = V _{CC} or GND	5.5 V			±0.1	±1		±1		µA
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.5	±5		±5		µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			8	80		80		µA
ΔI _{CC} [‡]	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9	1		1		mA
C _i	V _I = V _{CC} or GND	5 V		4.5						pF
C _o	V _O = V _{CC} or GND	5 V		16						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			54ACT16827		74ACT16827		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	3.6	7.4	9.8	3.6	11	3.6	11	ns
t _{PHL}			2.8	7.4	9.8	2.8	10.8	2.8	10.8	
t _{PZH}	$\overline{\text{OE}}$	Y	3	7.9	10.4	3	11.7	3	11.7	ns
t _{PZL}			4	9.6	12.4	4	14	4	14	
t _{PHZ}	$\overline{\text{OE}}$	Y	5.8	9.1	11.3	5.8	12.4	5.8	12.4	ns
t _{PLZ}			5.3	8.5	10.5	5.3	11.5	5.3	11.5	

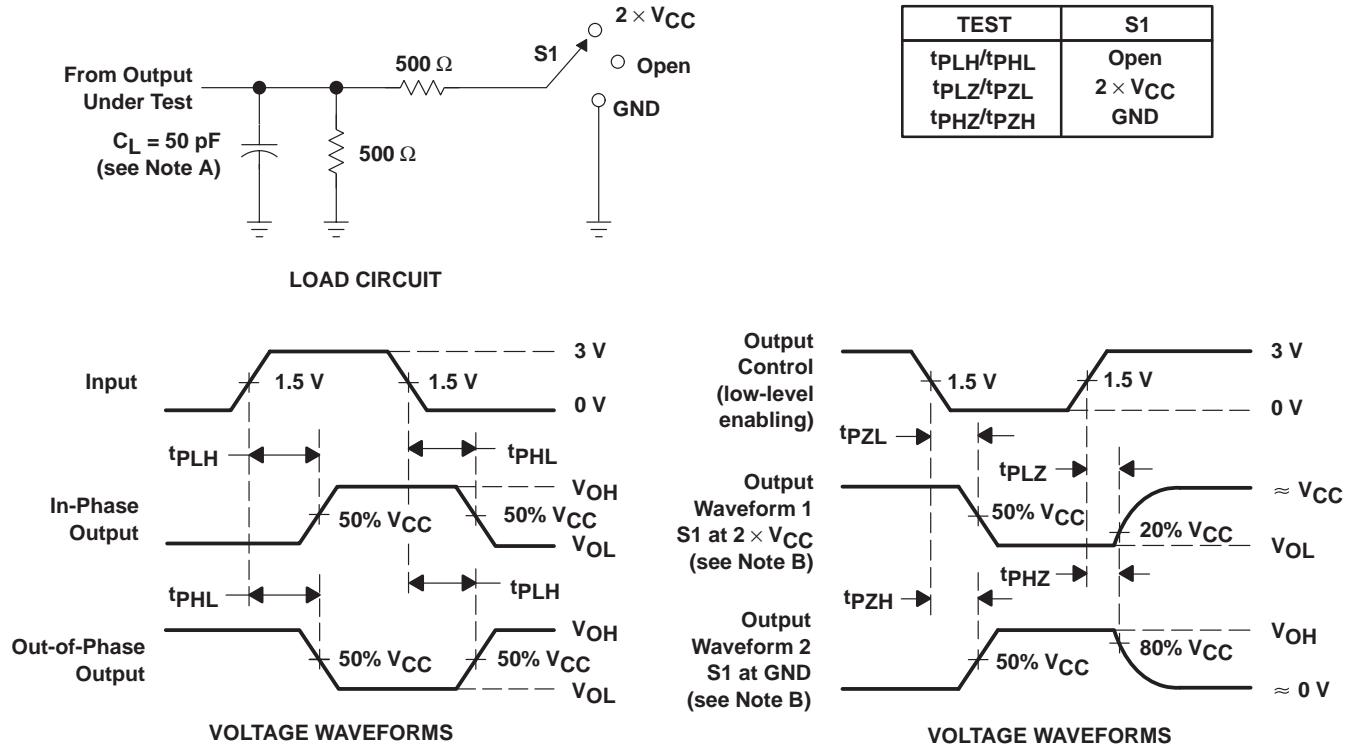
operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER			TEST CONDITIONS		TYP	UNIT
C _{pd}	Power dissipation capacitance	Outputs enabled	C _L = 50 pF, f = 1 MHz		41	pF
		Outputs disabled			10	

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.

D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ACT16827DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16827DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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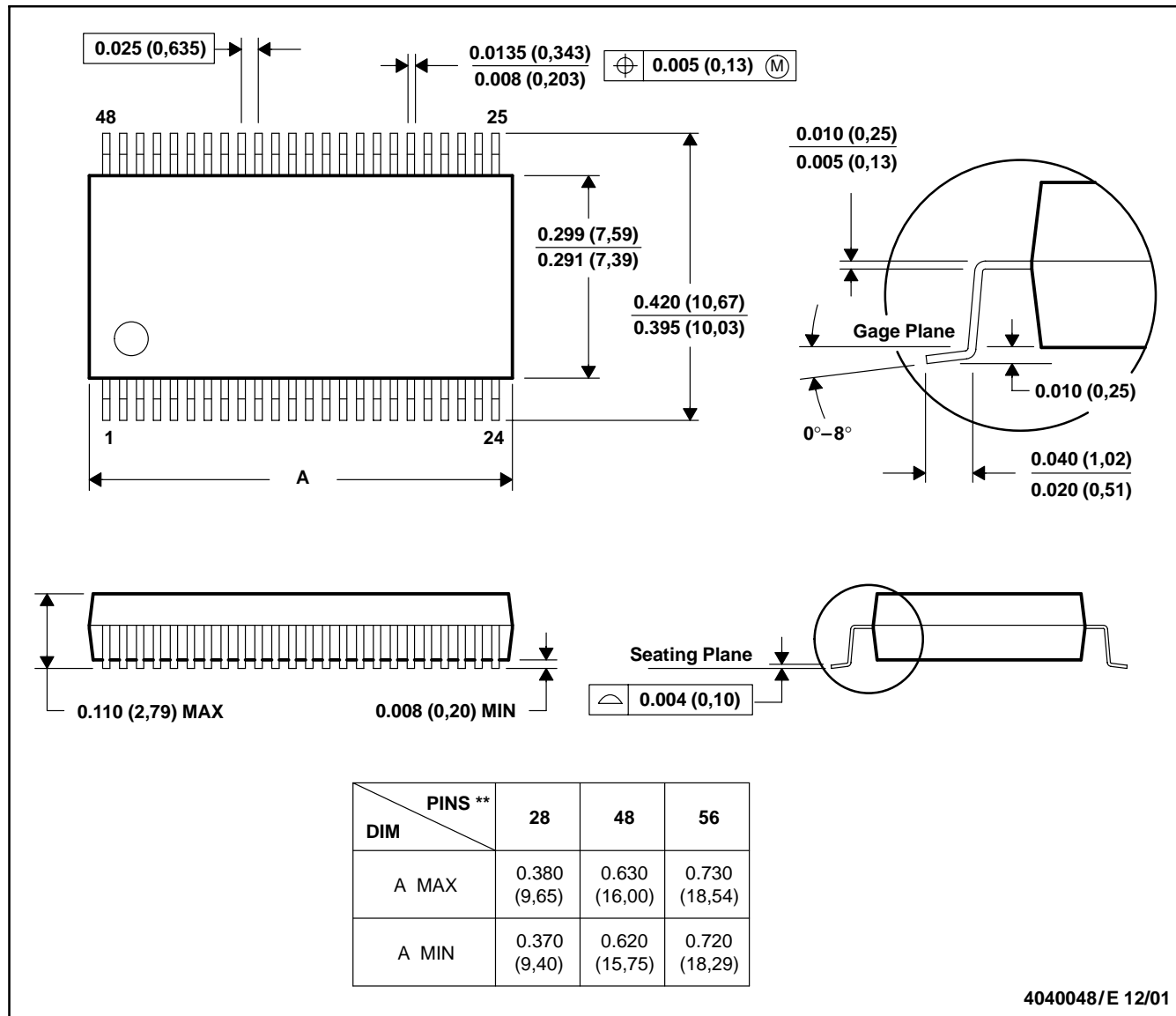
MECHANICAL DATA

MSS0001C – JANUARY 1995 – REVISED DECEMBER 2001

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118

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